

**IN THE CLAIMS**

This is a complete and current listing of the claims, marked with status identifiers in parentheses. The following listing of claims will replace all prior versions and listings of claims in the application.

1. (Previously Presented) An electronic power module, comprising:  
a first and a second cooling device;  
a semiconductor device, arranged between the first and the second cooling device;  
an elastic annular element, arranged around the semiconductor device, a space within the elastic annular element being encapsulated and being partially bounded by the first and second cooling devices, and the semiconductor device being located in the space.
2. (Previously Presented) The electronic power module as claimed in claim 1, wherein with the first and second cooling devices each include at least one heat sink.
3. (Previously Presented) The electronic power module as claimed in claim 1, wherein at least one of the first and second cooling device include a metal rail for directly transporting heat away from the semiconductor device and for making electrical contact with the semiconductor device.
4. (Previously Presented) The electronic power module as claimed in claim 3, wherein the respective metal rail and the at least one heat sink are integral.
5. (Previously Presented) The electronic power module as claimed in claim 3, wherein the respective metal rail and the at least one heat sink are composed of at least one of copper and aluminum.

6. (Previously Presented) The electronic power module as claimed in claim 1, wherein the semiconductor device includes two semiconductor elements electrically connected back-to-back in parallel.
7. (Previously Presented) The electronic power module as claimed in claim 6, wherein the semiconductor elements are in the form of semiconductor cells without a housing.
8. (Previously Presented) The electronic power module as claimed in claim 1, wherein the annular element is composed of rubber.
9. (Previously Presented) The electronic power module as claimed in claim 1, wherein the annular element is of a size which is substantially constant in the axial direction, so that a prespecified air gap and creepage distance are ensured between the first and second cooling devices.
10. (Previously Presented) The electronic power module as claimed in claim 1, wherein the annular element includes an opening or cutout through which at least one of lines for triggering a thyristor are passed and an encapsulation compound is introduced.
11. (Previously Presented) A method for producing an electronic power module, comprising:
  - arranging a semiconductor device between a first and a second cooling device;
  - arranging an elastic annular element around the semiconductor device, with a space being produced within the annular element, the space being partially bounded by the first and second cooling devices and the semiconductor device being located in the space; and
  - encapsulating the space with an encapsulation compound.
12. (Previously Presented) The method as claimed in claim 11, wherein the annular element, before encapsulation, creates a space between the two cooling devices in such a

way that at least one of a prespecified air gap and creepage distance is ensured between the first and the second cooling device.

13. (Previously Presented) The electronic power module of claim 1, wherein the electronic power module is for an electronic motor controller for a soft-starting motor.

14. (Previously Presented) The electronic power module as claimed in claim 2, wherein at least one of the first and second cooling device include a metal rail for directly transporting heat away from the semiconductor device and for making electrical contact with the semiconductor device.

15. (Previously Presented) The electronic power module as claimed in claim 4, wherein the respective metal rail and the at least one heat sink are composed of at least one of copper and aluminum.

16. (Previously Presented) The method of claim 11, wherein the electronic power module is for an electronic motor controller for a soft-starting motor.